L Number	Hits	Search Text	DB	Time stamp
1	6629	((copper or cu) near3 (layer or film or panel or coating)) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:47
2	4694	(((copper or cu) near3 (layer or film or panel or coating)) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5)) and ((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:57
3	1533	((((copper or cu) near3 (layer or film or panel or coating)) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5)) and ((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5))) and (circuit adj board$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:50
4	1020	(((((copper or cu) near3 (layer or film or panel or coating)) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5)) and ((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5))) and (circuit adj board$3)) and (mask$5 or resist or photomask$5 or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:06
5	161	((((((copper or cu) near3 (layer or film or panel or coating)) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5)) and ((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5) near5 (via$3 or hole$3 or trench$3 or opening$3 cavit$5))) and (circuit adj board$3)) and (mask$5 or resist or photomask$5 or photoresist)) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
6	19698	((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (laser or drill$5) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:03
7	1118	(((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (laser or drill$5) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5))) and (circuit adj board$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:59
8	7	((((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (laser or drill$5) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5))) and (circuit adj board$3)) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:00
9	993673	(dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:04

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10	73388	((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:04
11	19413	(((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
12	1924	((((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
13	1229	(((((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and (mask$5 or resist or photomask$5 or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:06
15	93	((((((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and (mask$5 or resist or photomask$5 or photoresist)) and blind	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:07
14	121	(((((dielectric or base or core or board or insulat$5 or non$2conduct$5 or epoxy or polymer$3 or resin$5 or body) near5 (via$3 or hole$3 or trench$3 or opening$3 or cavit$5)) and (circuit adj board$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and blind	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:07